Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A copper foil provided with an ultra thin primer resin layer for securing good laminating adhesiveness with a resin base material on one side of a copper foil without roughening treatment, where in,

a copper foil with an ultra thin adhesive layer for a printed wiring board is characterized in that a ultra thin primer resin layer of a converted thickness of 1 to 5 μm is provided on a surface of a copper foil having a surface roughness (Rz) of 2 μm or less not undergone said roughening treatment.

2. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, comprising a silane coupling agent layer on the surface of the copper foil provided with the ultra thin primer resin layer.

3. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2, wherein said silane coupling agent layer is formed using an amino-based silane coupling agent or a mercapto-based silane coupling agent.

4. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein said ultra thin primer resin layer is formed using a resin mixture consisting of 20 to 80 parts by weight of an epoxy resin (containing a curing agent), 20 to 80 parts by weight of a solvent-soluble aromatic

polyamide resin polymer, and an appropriate quantity added as required of a curing accelerator.

5. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 4, wherein said aromatic polyamide polymer using for said ultra thin primer resin layer is obtained by allowing an aromatic polyamide to react with a rubber-like resin.

6. (Currently Amended) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein said ultra thin primer resin layer is formed using a resin mixture consisting of ~~20~~ 5 to 50 parts by weight of an epoxy resin (containing a curing agent), 50 to 95 parts by weight of a polyether sulfon resin (having a hydroxyl group or an amino group at an proximal end, and soluble in a solvent), and an appropriate quantity added as required of a curing accelerator.

7. (Original) The copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1, wherein the resin flow when measured in accordance with MIL-P-13949G in the MIL Standard is 5% or less.

8. (Original) A method for manufacturing a copper foil with an ultra thin adhesive layer for a printed wiring board characterized in that a resin solution used in the formation of an ultra thin primer resin layer is prepared by the procedures of the following Step a and Step b; and a converted thickness of 1 to 5 μm of said resin solution is applied onto a surface of a copper foil on which a silane coupling agent layer is formed, and dried to be in a semi-cured state comprising the Step a.
and the Step b.:

Step a. An epoxy resin (containing a curing agent), an aromatic polyamide polymer soluble in a solvent, or a polyether sulfon resin, and an appropriate quantity added as required of a curing accelerator being mixed to form a resin mixture.

Step b. Said resin mixture being dissolved using an organic solvent to form a resin solution of a resin solid content of 10% by weight to 40% by weight.

9. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 1.

10. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 2.

11. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 3.

12. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 4.

13. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 5.

14. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 6.

15. (Original) A copper-clad laminate using a copper foil with an ultra thin adhesive layer for a printed wiring board according to claim 7.